

**FLIP CHIP PACKAGE WITH HEAT SPREADER ALLOWING MULTIPLE  
HEAT SINK ATTACHMENT**

**Abstract of the Disclosure**

A chip package is provided with multiple ways of attaching a heat sink  
5 directly to the chip carrier. Corner post are mounted to the surface of the chip  
carrier. A heat spreading plate, with a surface area substantially the same size  
as the surface area of the chip carrier, is positioned in thermal contact with the  
surface of a flip chip, for example. The heat spreading plate has corner cuts to  
accommodate the corner posts of the chip carrier and notches cut into at least  
10 two opposing sides. A heat sink plate with holes extending therethrough at  
each of its four corners is positioned to allow the corner posts of said chip  
carrier to extend therethrough. Notches cut in two opposing sides of said heat  
sink plate are aligned with the notches in said heat spreading plate to create  
slots for a flexible clip to clamp the assembly together. Alternatively, nuts may  
15 also be threaded onto the posts to clamp the assembly together.